

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_

PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_

MODEL NO 型号: \_\_\_\_\_ HDF823A-F11 \_\_\_\_\_

PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_

APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2006-5-11 \_\_\_\_\_

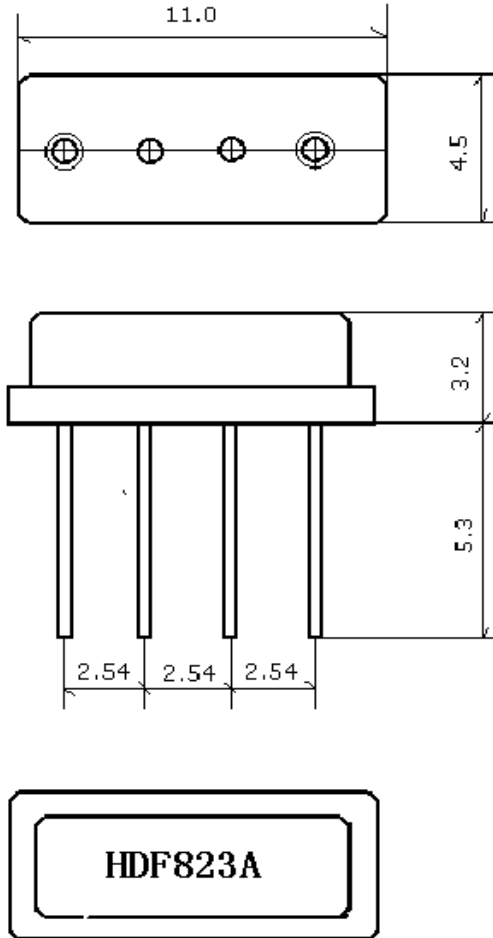
客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



**1. Package Dimension**

Unit:mm



**2. Marking**

HD F823A

- 2.1 Color: Black or Blue
- 2.2 823: Center Frequency(MHz)

**3. Performance**

3.1 Application

Low-Loss SAW Filter of cordless system.  
Center Frequency:823MHz

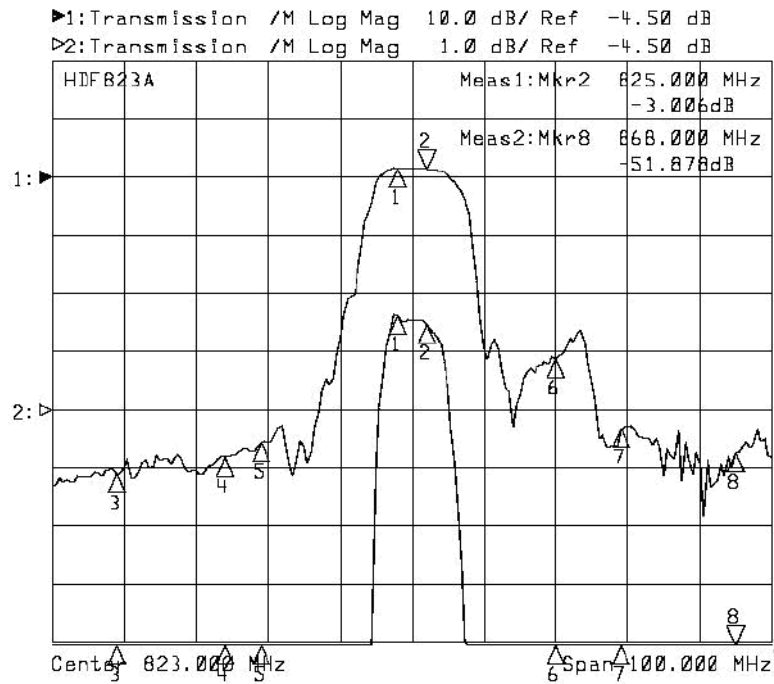
3.2 Maximum Rating

Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
DC. Voltage	10 V
Maximum Input Power	5 dBm

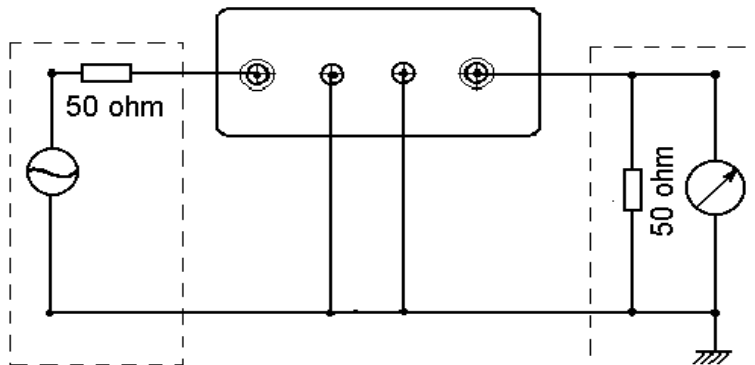
3.3 Electronic Characteristics

Item	Specification
Center Frequency(fo)	823 MHz
Insertion Loss(dB)	
1.)821-825 MHz	4.5max
2.)772-782 MHz	40 min
3.)797-802 MHz	30 min
4.)843-852 MHz	20 min
5.)868~902MHz	40 min
Ripple deviation (821-825MHz)(dB)	1.5max
Input/output Impedance(Nominal)	50Ω

3.4 Frequency Characteristics



3.5 Test Circuit



## **4. ENVIRONMENTAL CHARACTERISTICS**

### 4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

### 4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

### 4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +80°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.3.

### 4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C  $\pm$ 10°C for 10 $\pm$ 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.3.

### 4-5 Solderability

Subject the device terminals into the solder bath at 245°C  $\pm$ 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.3.

### 4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 3.3.

### 4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.3.

## **5. REMARK**

### 5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 5.3 Soldering

Only leads of component may be soldered . Please avoid soldering another part of component.